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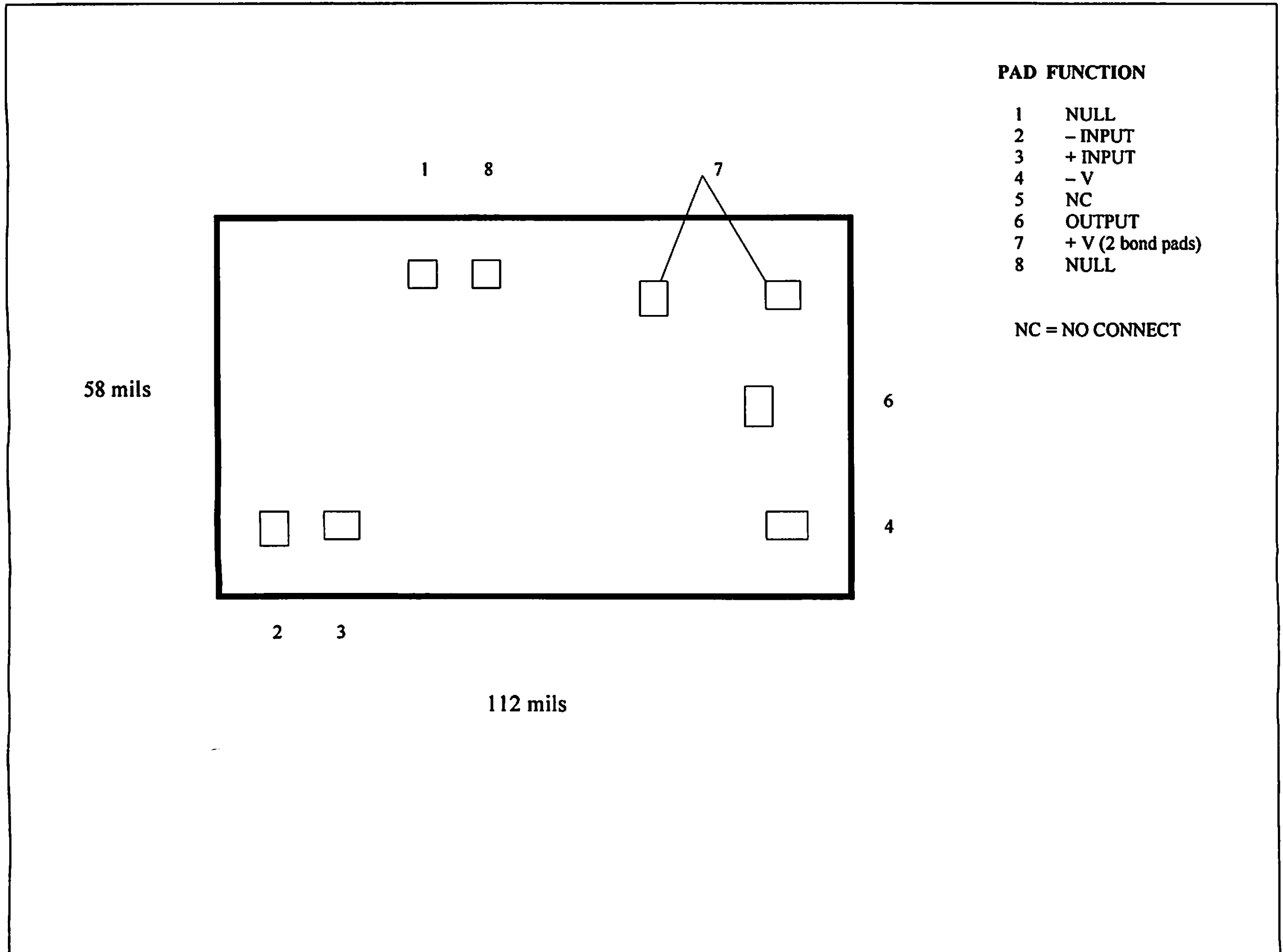
DiTech

Striving for perfection
in service to the Hybrid Industry



The information given is believed to be correct at the time of issue.
Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.
Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.
Pad positions shall obey the following rules:

1. Pad functions shall not change sequence and shall agree with the above definitions.
2. No pad function shall move by more than 1mm from the position shown.
3. No pad function shall move from a corner, and another move into that corner, even if the above constraints are met.

Note: 1 mil = 0.001inch

APPROVED		DIE INFORMATION
G.B .... DATE: 7.2.01	AD845J ANALOG DEVICES	DIMENSIONS (Mils): 112 x 58 x 24 BOND PADS (Mils): 4 x 4 min MASK. REF: GEOMETRY: BACK POTENTIAL: -V
SERIAL NUMBER. 004911		METALLISATION TOP: Al BACK: Si